

REMARKS

Claims 1-17 are now in the application. Claims 8-17 are directed to the elected invention. Claims 1-7 are drawn to a non-elected invention and may be cancelled by the Examiner upon the allowance of a claims directed to the elected invention. Claims 8-17 have been amended to include commas and colons as suggested by the Examiner, thereby addressing the objections to these claims.

Claims 8-12 and 14-17 were rejected under 35 U.S.C. 103(a) as being unpatentable over U.S. Patent 6,201,194 to Lauffer et al. in view of U.S. Patent 6,175,087 to Keesler. Claim 13 was rejected under 35 U.S.C. 103(a) as being unpatentable over Lauffer and Keesler in further view of U.S. Patent 5,719,354 to Jester. These rejections of the claims have been overcome by the filing of the attached Declaration of Common Ownership. In particular, the present application and US patent 6,201,194 were, at the time the invention of this application was made, owned by International Business Machines Corporation. In addition, an assignment to this application to International Business Machines Corporation has been recorded in the USPTO at Reel 011028 Frame 0255(copy attached). In view of the Declaration, the rejections over Lauffer et al have been eliminated because the present application was filed prior to the issuance of Lauffer et al. See 35 USC 103(c) and MPEP 706.02(l)(1) and 706.02(l)(2). The filing of the Declaration is not to be construed as an admission, acquiescence or estoppel with respect to the rejections over Lauffer et al. For example, see Quad Enviromental Tech. V. Union Sanitary District 20 USPQ2d 1474(Fed. Cir. 1991) which discussed the filing of a

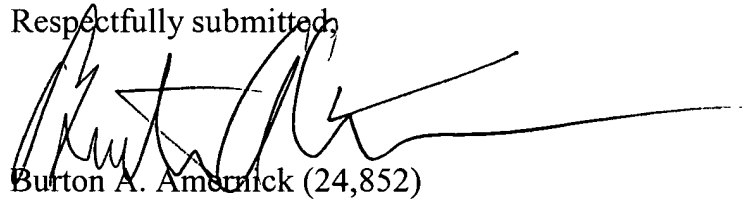
Terminal Disclaimer. The filing of the Declaration in the present case is deemed somewhat analogous to that situation.

In view of the above, consideration and allowance are, therefore, respectfully solicited.

In the event the Examiner believes an interview might serve to advance the prosecution of this application in any way, the undersigned attorney is available at the telephone number noted below.

The Director is hereby authorized to charge any fees, or credit any overpayment, associated with this communication, including any extension fees, to Deposit Account No. 22-0185.

Respectfully submitted,

A handwritten signature in dark ink, appearing to read 'Burton A. Amernick', with a long horizontal flourish extending to the right.

Burton A. Amernick (24,852)
Connolly Bove Lodge & Hutz LLP
1990 M Street, N.W.
Washington, D.C. 20036-3425
Telephone: 202-331-7111

Date: 4-8-02



APPENDIX-MARKED-UP VERSION OF AMENDED CLAIMS

8.(Amended) A method for fabricating a laminate circuit structure assembly which comprises: providing at least two modularized circuitized voltage plane subassemblies wherein each of the subassemblies comprise at least two signal planes having an external and internal surface disposed about an internal voltage plane; providing dielectric between the signal and voltage planes; and providing dielectric on each external surface of each signal plane; and providing a non-cured or partially cured curable dielectric composition between the subassemblies wherein the dielectric composition comprises, the same dielectric used in said subassemblies, aligning the subassemblies, and then laminating to cause bonding of the subassemblies.

9.(Amended) The method of Claim 8, which further comprises: locating an interposer between the subassemblies wherein the interposer comprises dielectric layers disposed about an internal electrically conductive layer.

10.(Amended) The method of Claim 9, wherein dielectric of at least one of the surfaces that is to be bonded is from said dielectric composition.

11.(Amended) The method of Claim 8, wherein vias are disposed within each subassembly for providing electrical communication between signal planes and electrical connection to another subassembly.

12.(Amended) The method of Claim 11, wherein the vias through the signal planes are plated with a conductive metal.

13.(Amended) The method of claim 11, wherein the vias are filled with conductive adhesive.

14.(Amended) The method of Claim 9, wherein the internal electricity conductive layer of the interposer is copper.

15.(Amended) The method of Claim 9, wherein the interposer is about 3 to about 10 mils thick.

16.(Amended) The method of Claim 8, which comprises: providing top and bottom circuit layers on top and bottom external surfaces of the assembly.

17.(Amended) The method of Claim 8, wherein the laminating is carried out at about 100 to about 200°C, for about 15 minutes to about 90 minutes, and at a pressure of about 100 to about 500 psi.



part of #7

Robert M. Japp et al.

Serial No.: 09/625,135

Filed: July 25, 2000

For: Composite Laminate Circuit
Structure and Methods of
Fabricating

Art Unit: 3729

Examiner: Smith, S.

Atty Docket: END919990082US1

RECEIVED
APR 10 1954
TO 3703, BELL 10234

Commissioner for Patents
Washington, D.C. 20231

The undersigned attorney for the assignee of the entire right, title and interest of this application hereby declares that both the present application USSN 09/625,135 and US patent 6,201,194 B1 to Lauffer et al. were, at the time the invention of USSN 09/625,135 was made, owned by International Business Machines Corporation.

All statements made herein of my own knowledge are true. All statements made on information and belief are believed to be true. These statements were made with the knowledge that willful false statements and the like so made are punishable by fine, imprisonment, or both, under 18 U.S.C. 1001 and may jeopardize the validity of the application or any patent issuing thereon.

Respectfully submitted,


Burton A. Merrick (21852)

Burton A. Amernick (24,852)
Connolly Bove Lodge & Hutz LLP
1990 M Street, N.W.
Washington, D.C. 20036-3425
Telephone: 202-331-7111